[0049] Once plate **14** has been made, one electronic module **2**, which is electrically independent of the plate, is inserted into each aperture **16**. The electronic module and all the electrical connections thereof, are made beforehand. In the example described here, module **2** includes a substrate **12**, which extends into at least some zones at the edge of said module, beyond the electronic elements **4** to **8** which said module carries. The dimensions and shape of substrate **12** are such that it has two zones **24** which are superposed on the two projecting portions **18**, when electronic module **2** is inserted into aperture **16**. Thus, substrate **12** abuts against projecting portions **18**, as shown in FIG. **3**B.

[0050] According to the invention, electronic modules **2** are assembled to plate **14** in a sufficiently rigid manner, firstly, so that electronic modules **2** remain in apertures **16** during the card manufacturing method according to the invention, and secondly, so that they approximately maintain the initial position defined when projecting portions **18** are assembled. The electronic module can be positioned when it is inserted into aperture **16** relative to a defined reference on plate **14**. This positioning of module **2** relative to plate **14** may concern the module as a whole and thus in particular substrate **12**, or it may concern one particular element of the module, in particular electronic display **6**. This is particularly advantageous, given that display **6** is, by definition, meant to be visible on one surface of the finished card. Precise positioning of the display relative to the contour **20** of the card is important for aesthetic reasons, and also functional reasons, when the display appears through an aperture in a covering layer of the card. When positioning is required relative to the display, means are provided for marking electronic display **6** and then inserting module **2** in such a way that display **6** is in a determined position relative to plate **14**, which thus forms a positioning structure.

[0051] Electronic module **2** can be secured to projecting portions **18** in various ways. By way of example, provided that the materials forming the two zones **24** of substrate **12** and projecting portions **18** can adhere directly to each other, said zones **24** are simply heat welded to projecting portions **18**, using thermodes. Module **2** can also be secured to plate **14** using an ultrasound head or other means known to those skilled in the art. In another variant, an adhesive film is deposited, either on projecting portions **18**, or on zones **24**, so as to bond them to each other. In other variants, substrate **12** is secured to projecting portions by adding drops of adhesive or a strip of adhesive between the edge of the substrate and the projecting portions. Any chemical or physical means that assemble module **2** to the projecting portions in a sufficiently rigid manner can be used within the scope of the present invention.

[0052] A secure assembly is thus obtained, formed of plate **14** and electronic modules **2**, which are housed in apertures **16** of the plate. Two particular, advantageous features of assembly **22** will be noted:

[0053] firstly, the thickness of module **2** is substantially identical to the thickness of plate **14**, electronic module **2** being entirely housed in the corresponding aperture **16**;

[0054] secondly, a slot **26** remains between module **2** and the edge of aperture **16**, with the exception of the zones where projecting portions **18** are located.

[0055] The fact that module **2** is housed entirely inside aperture **16**, i.e. in the thickness of plate **14**, means that the manufacture of relatively thin cards can be better controlled. This means cards that have the smallest possible increase in thickness relative to the thickness of module **2**. The presence of a slot **26** reduces manufacturing tolerances for pierced plate **14** and modules **2** and also allows substrate **12** to be positioned slightly differently from one aperture to another, depending upon the position of the electronic display assembled to the substrate. Moreover, as will become clear below, slots **26** can then be filled by a resin, which thus provides an adherent bridge between substrate **12** and the wall of through aperture **16**. This ensures, finally, that electronic module **2** and plate **4** are perfectly secured to each other, such that, when the finished card is bent or subjected to other stress, electronic module **2** follows the deformation of plate **14** properly. This prevents the edges of substrate **12** of module **2** marking the external surfaces of the finished card and thus damaging the aesthetic appearance of the card. It will be noted that the material used, in particular for making substrate **12**, is selected so that it can withstand a certain amount of elastic deformation and can allow electronic module **2** to be bent, when the card is subjected to stress, particularly within the scope of tests carried out to ensure compliance with the relevant standards.

[0056] A first alternative embodiment is shown in FIG. **5**, which shows a single aperture **16** of a plate **14**, which here has approximately the dimensions of a single card. This simplified diagram, which is also used in FIGS. **6** and **8**, is in no way restrictive, and describes an assembly **30**, which is similar to assembly **22** of FIG. **4**, i.e. for batch manufacturing a plurality of cards.

[0057] The variant of FIG. **5** differs in that the projecting portions **18**A are formed in the four corners of aperture **16**. The portions thus define truncated corners in the bottom area of aperture **16**. Projecting portions **18**A, which project relative to the generally rectangular shape of aperture **16**, can be made by the same, aforementioned techniques. The dimensions of module **2** are such that the four corners of substrate **12** are superposed on the four parts **18**A. The electronic module is assembled to plate **14** in a similar manner to the previously described variant.

[0058] FIG. **6** shows a second alternative embodiment of the assembly according to the invention. This alternative is characterized in that it provides a step **34**, which forms an intermediate level against which two lateral zones **36** of substrate **12** abut, along two opposite edges of rectangular aperture **16**. Steps **34** can be formed in a similar manner to the projecting portions described in the other variants. The electronic module is assembled to plate **14** by welding or bonding, or by any other physical or chemical means available to those skilled in the art.

[0059] FIGS. **7**A and **7**B show an assembly according to a third variant of the first embodiment. Frame **14** includes a plurality of apertures **16**. The peripheral area of each aperture has at least one notch **38** or preferably at least two notches **38**. Each notch defines a small circular step. Electronic module **2** has projecting portions **40** at the edge thereof, which are partially superposed on notches **38** when module **2** is inserted in aperture **16**. These projecting portions **40** rest on the small circular steps **38**. Module **2** is assembled to plate **14** via zones **40**, which are either welded, or bonded in notches **38**. In a particular variant, the notches are sized such that projecting zones **40** have to be forcibly pushed into these notches, which secures electronic module **2** to plate **14**. However, this latter variant has the drawback of requiring substrate **12** and notches **38** to be machined very precisely in the peripheral